



General Specifications

Resistive Element:	Thick film
Substrate:	Beryllium oxide ceramic
Cover:	Alumina ceramic
Mounting Flange:	Copper, nickel plated per QQ-N-290
Lead(s):	99.99% pure silver (.005" thk)

Features

- DC - 500 MHz
- 400 Watts
- BeO Ceramic
- Welded Silver Leads
- Non-Nichrome Resistive Element
- Low VSWR
- 100% Tested

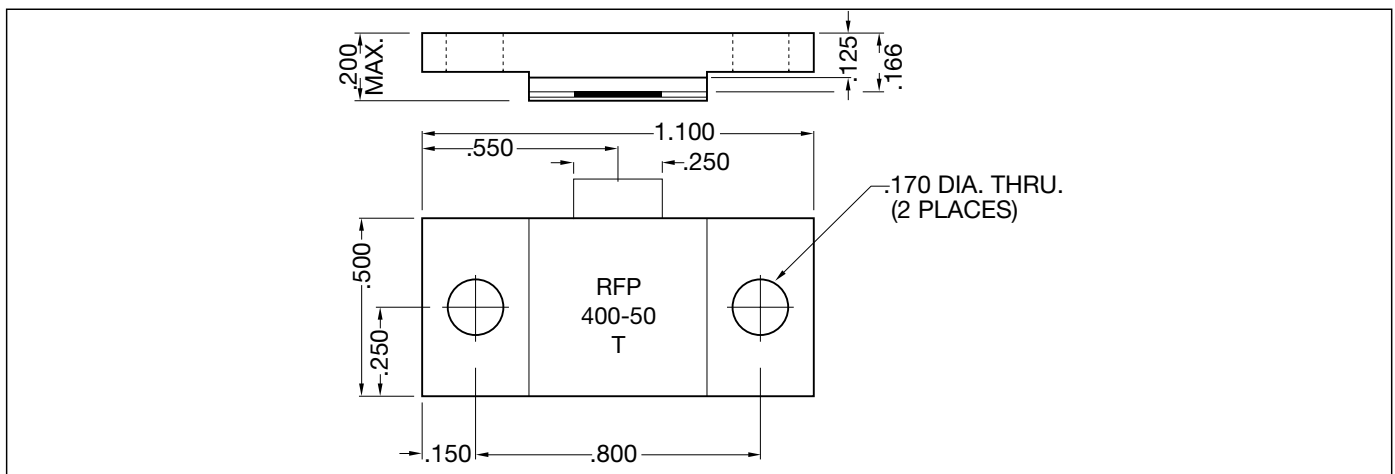
Electrical Specifications

Resistance Value:	50 ohms, ±5%
Frequency Range:	DC - 500 MHz
Power:	400 Watts
V.S.W.R.:	1.30:1

Notes: Tolerance is ±.010, unless otherwise specified. Operating temperature is -55°C to +150°C (see chart). Designed to meet or exceed applicable portions of MIL-E-5400. All dimensions are in inches. Lead length 0.15" minimum.

Specifications subject to change without notice.

Outline Drawing



VER. 12/5/01

Sales Desk USA: Voice: (800) 544-2414 Fax: (315) 432-9121
 Sales Desk Europe: Voice: (+44) 23 92 232392 Fax: (+44) 23 92 251369

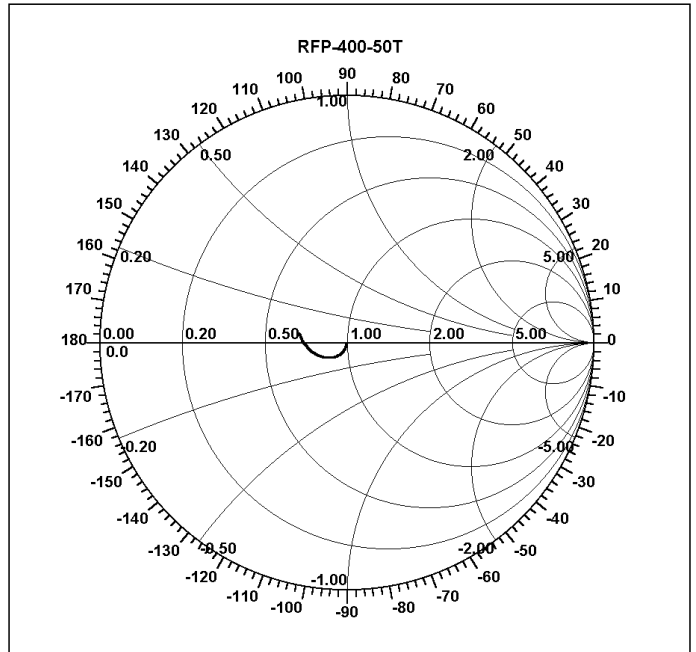
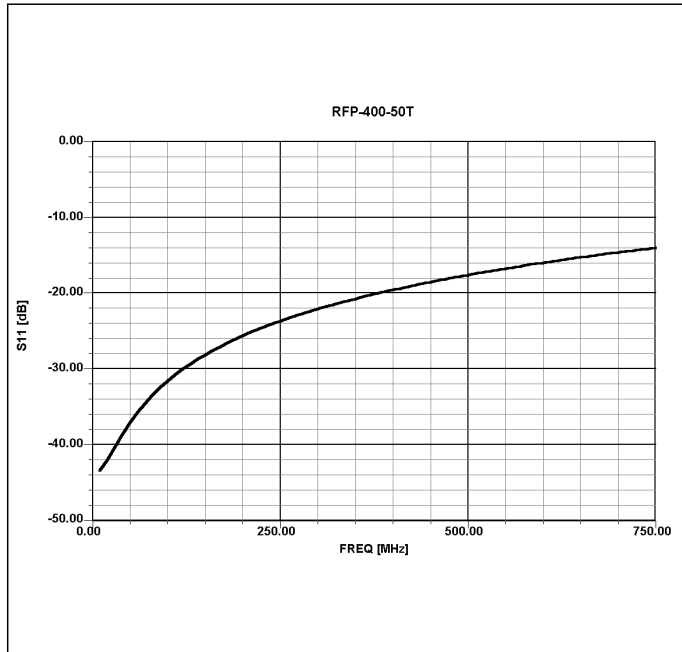
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 What'll we think of next?™

Model RFP-400-50T

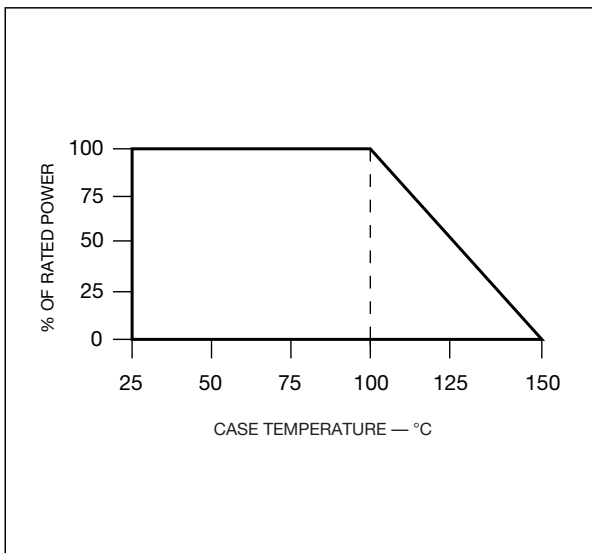
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RF Power

Typical Performance



Power Derating



Suggested Mounting Procedures

BOARD LOWER THAN LEAD.

BOARD EVEN WITH LEAD.

SUGGESTED STRESS RELIEF METHODS

SCALE: ~

BOARD LOWER THAN LEAD.

BOARD HIGHER THAN LEAD.

NOT RECOMMENDED APPLICATION

SCALE: ~

1. Make sure that the devices are mounted on flat surfaces (.001" under the device) to optimize the heat transfer.
2. Drill & tap the heatsink for the appropriate thread size to be used.
3. Coat heatsink with a minimum amount of high quality silicone grease (.001" max. thickness).
4. Position device on mounting surface and secure using socket head screws, flat & split washers. Torque screws to the appropriate value. Make sure that the device is flat against the heatsink. (Care should be taken to avoid upward pressure of the leads towards the lid).
5. Solder leads in place using an SN63 type solder with a controlled temperature iron (210°C).